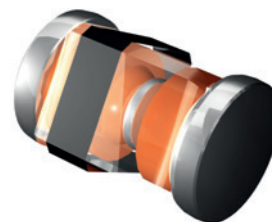


Features

- Fast switching speed
- Surface mount package ideally suited for automatic insertion
- Silicon epitaxial planar construction
- Lead free in compliance with EU RoHS 2002/95/EU directive

Mechanical Data

- Case: Micro MELF
- Terminals: Solderable per MIL-STD-750, method 2026
- Polarity: Cathode band



Micro MELF

Maximum Ratings (T_A=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V _{RM}	100	V
Maximum DC Blocking Voltage	V _{DC}	75	V
Maximum Average Forward Current at T _A =25°C and f ≥50Hz	I _(AV)	150	mA
Surge Forward Current at t<1s and T _J =25°C	I _{FSM}	500	mA
Power Dissipation at T _A =25°C	P _{TOT}	500	mW
Typical Thermal Resistance	R _{θJA}	350	°C/W
Junction Temperature and Storage Temperature Range	T _J , T _{stg}	-65 to +175	°C

Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Max.	Unit
Forward Voltage	V _F	I _F =100mA	1.0	V
Leakage Current	I _R	V _R =20V	25	nA
		V _R =20V, T _J =150°C	50	uA
Capacitance	C _J	V _F =V _R =0, f=1MHz	4	pF
Reverse Recovery Time	t _{rr}	I _F =-I _R =10mA to I _{RR} =-1mA, V _R =6V, R _L =100Ω	4	ns

Ratings and Characteristic Curves

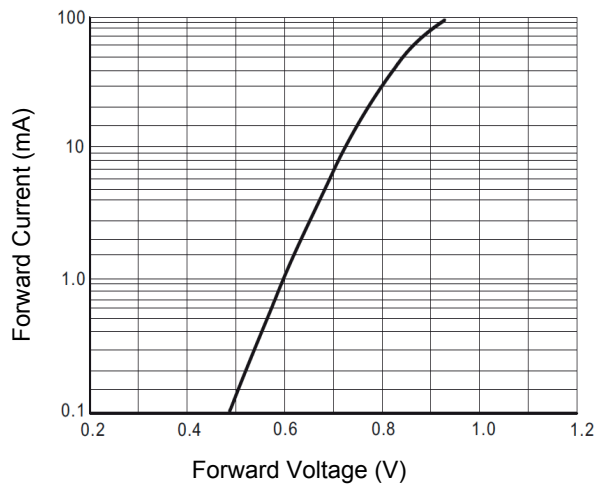


Figure 1. Forward Voltage

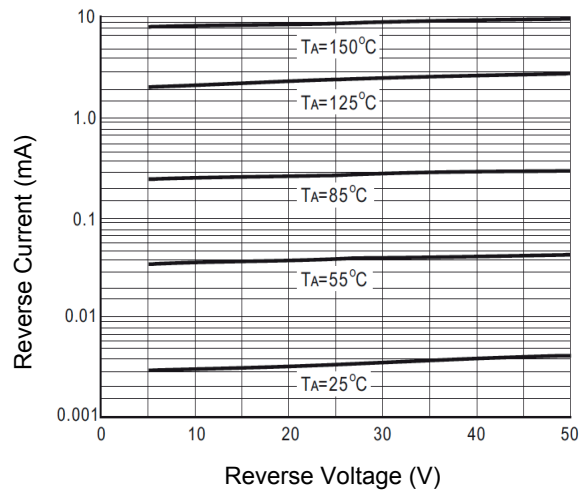


Figure 2. Leakage Current

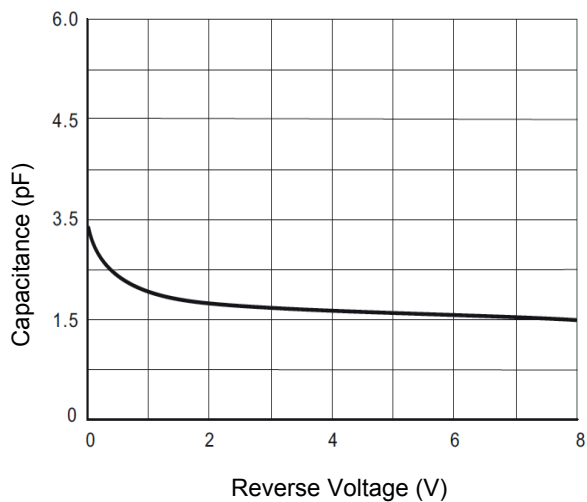
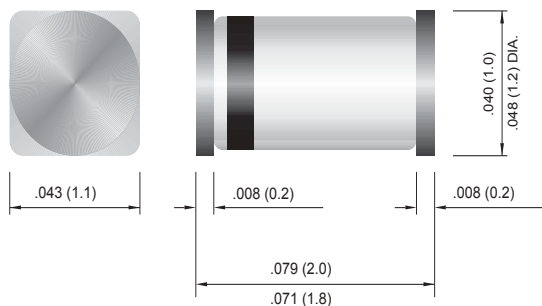


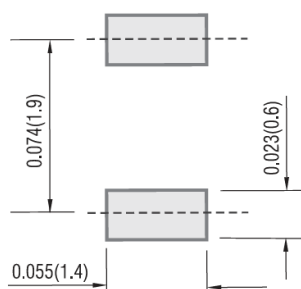
Figure 3. Typical Capacitance

Package Outline Dimensions (Micro MELF)



Unit: inch (mm)

Recommended Pad Layout



Unit: inch (mm)

Order Information

Device	Package	Marking	Carrier	Quantity
GSMCL4448	Micro MELF	Cathode line	Tape & Reel	3,000 Pcs / Reel